



N-Channel Enhancement MOSFET

VDS= 60V, ID= 115mA



FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.

MARKING

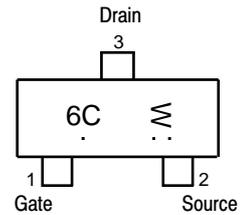
6C

PACKAGE INFORMATION

Package	Shipping
SOT-323	3000/Tape&Reel

MARKING DIAGRAM & PIN ASSIGNMENT

SOT-323 (SC-70)



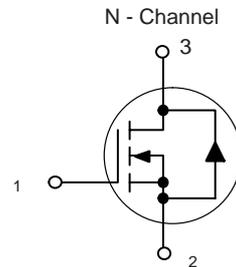
6C = Device Code
M = Work Week

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	60	V _{dc}
Drain-Gate Voltage ($R_{GS} = 1.0 \text{ M}\Omega$)	V_{DGR}	60	V _{dc}
Drain Current - Continuous $T_C = 25^\circ\text{C}$ (Note 1.) $T_C = 100^\circ\text{C}$ (Note 1.) - Pulsed (Note 2.)	I_D I_{DM}	± 115 ± 75 ± 800	mAdc
Gate-Source Voltage - Continuous - Non-repetitive ($t_p \leq 50 \mu\text{s}$)	V_{GS} V_{GSM}	± 20 ± 40	V _{dc} V _{pk}

115 mAMPS
60 VOLTS

$R_{DS(on)} = 7.5 \Omega$



THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 3.) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation Alumina Substrate, (Note 4.) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

1. The Power Dissipation of the package may result in a lower continuous drain current.
2. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.
3. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
4. Alumina = $0.4 \times 0.3 \times 0.025$ in 99.5% alumina.

2N7002W

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
----------------	--------	-----	-----	-----	------

OFF CHARACTERISTICS

Drain–Source Breakdown Voltage (V _{GS} = 0, I _D = 10 μAdc)	V _{(BR)DSS}	60	–	–	Vdc
Zero Gate Voltage Drain Current (V _{GS} = 0, V _{DS} = 60 Vdc)	I _{DSS}	–	–	1.0 500	μAdc
Gate–Body Leakage Current, Forward (V _{GS} = 20 Vdc)	I _{GSSF}	–	–	100	nAdc
Gate–Body Leakage Current, Reverse (V _{GS} = –20 Vdc)	I _{GSSR}	–	–	–100	nAdc

ON CHARACTERISTICS (Note 2.)

Gate Threshold Voltage (V _{DS} = V _{GS} , I _D = 250 μAdc)	V _{GS(th)}	1.0	1.6	2.5	Vdc
On–State Drain Current (V _{DS} ≥ 2.0 V _{DS(on)} , V _{GS} = 10 Vdc)	I _{D(on)}	500	–	–	mA
Static Drain–Source On–State Voltage (V _{GS} = 10 Vdc, I _D = 500 mAdc) (V _{GS} = 5.0 Vdc, I _D = 50 mAdc)	V _{DS(on)}	–	–	3.75 0.375	Vdc
Static Drain–Source On–State Resistance (V _{GS} = 10 V, I _D = 500 mAdc) T _C = 25°C (V _{GS} = 10 V, I _D = 500 mAdc) T _C = 125°C (V _{GS} = 5.0 Vdc, I _D = 50 mAdc) T _C = 25°C (V _{GS} = 5.0 Vdc, I _D = 50 mAdc) T _C = 125°C	r _{DS(on)}	–	1.4 – 1.8 –	7.5 13.5 7.5 13.5	Ohms
Forward Transconductance (V _{DS} ≥ 2.0 V _{DS(on)} , I _D = 200 mAdc)	g _{FS}	80	–	–	mmhos

DYNAMIC CHARACTERISTICS

Input Capacitance (V _{DS} = 25 Vdc, V _{GS} = 0, f = 1.0 MHz)	C _{iss}	–	17	50	pF
Output Capacitance (V _{DS} = 25 Vdc, V _{GS} = 0, f = 1.0 MHz)	C _{oss}	–	10	25	pF
Reverse Transfer Capacitance (V _{DS} = 25 Vdc, V _{GS} = 0, f = 1.0 MHz)	C _{rss}	–	2.5	5.0	pF

SWITCHING CHARACTERISTICS (Note 2.)

Turn–On Delay Time	(V _{DD} = 25 Vdc, I _D ≅ 500 mAdc, R _G = 25 Ω, R _L = 50 Ω, V _{gen} = 10 V)	t _{d(on)}	–	7	20	ns
Turn–Off Delay Time		t _{d(off)}	–	11	40	ns

BODY–DRAIN DIODE RATINGS

Diode Forward On–Voltage (I _S = 11.5 mAdc, V _{GS} = 0 V)	V _{SD}	–	–	–1.5	Vdc
Source Current Continuous (Body Diode)	I _S	–	–	–115	mAdc
Source Current Pulsed	I _{SM}	–	–	–800	mAdc

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

DEVICE CHARACTERISTICS

2N7002W

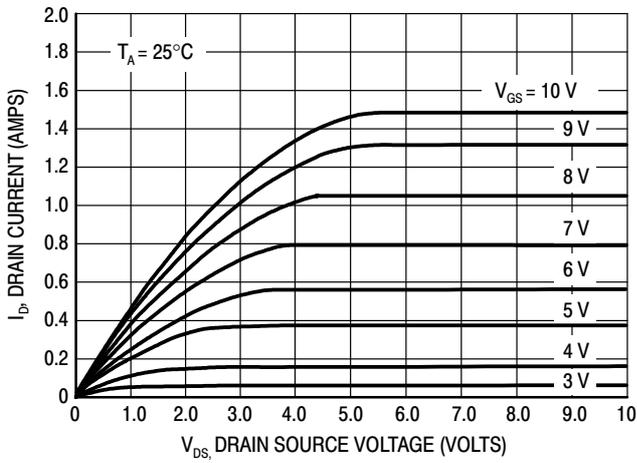


Figure 1. Ohmic Region

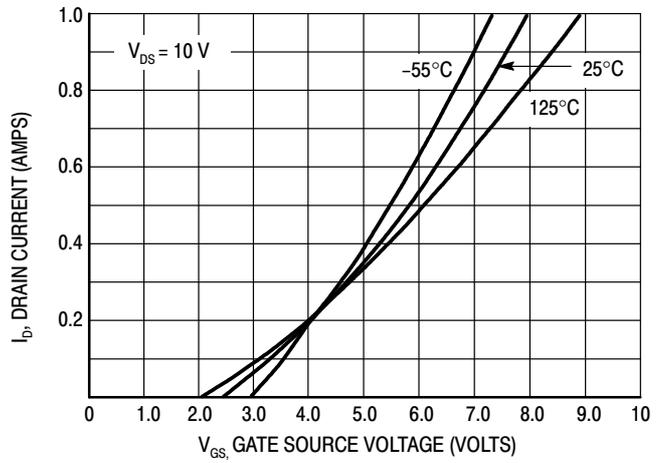


Figure 2. Transfer Characteristics

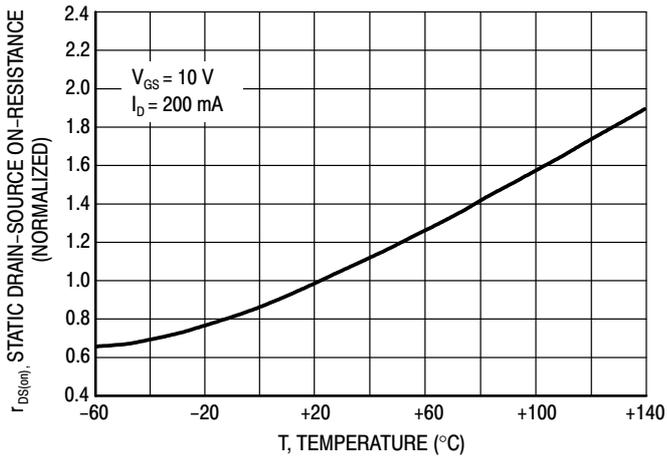


Figure 3. Temperature versus Static Drain-Source On-Resistance

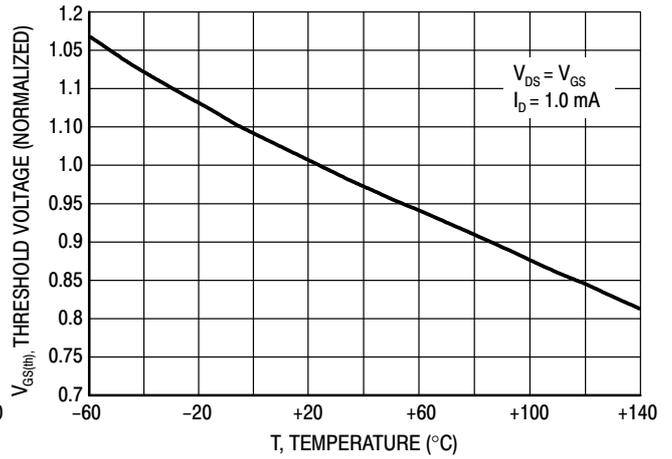


Figure 4. Temperature versus Gate Threshold Voltage

PACKAGE OUTLINE & DIMENSIONS

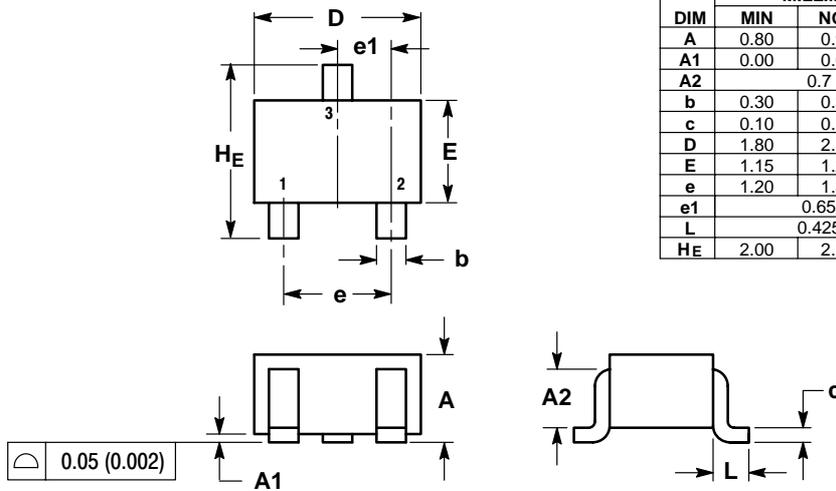
2N7002W

SOT-323 (SC-70)

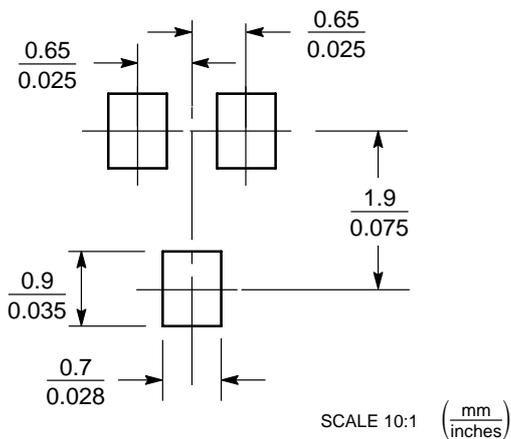
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

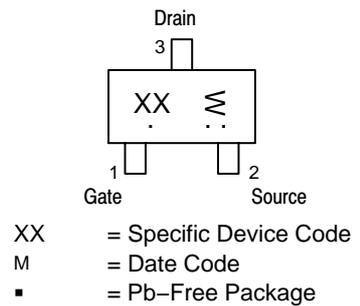
DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.7 REF			0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.425 REF			0.017 REF		
HE	2.00	2.10	2.40	0.079	0.083	0.095



SOLDERING FOOTPRINT*



GENERIC MARKING DIAGRAM



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.